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Features

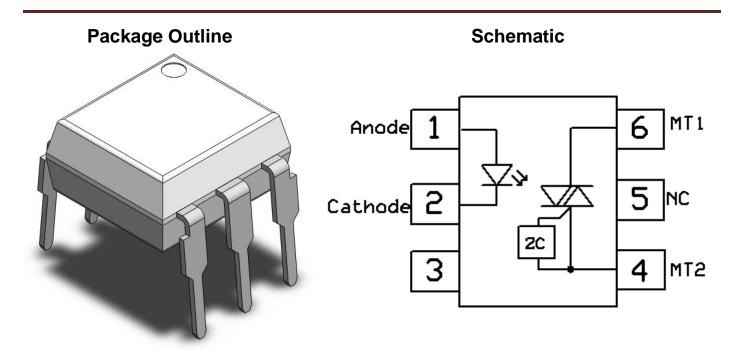
- High isolation 5000 VRMS
- Peak Breakdown Voltage
 - 600V CT3061,3062,3063
 - 800V CT3081,3082,3083
- Temperature range 55 °C to 100 °C
- External Creepage ≥ 7.0mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 8.0mm (M/SLM Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (40039590)
 - ✓ CQC GB4943.1, GB8898 (14001105802)
 - ✓ IEC62368 (FI/41119)

Description

The CT3061, CT3062, CT3063, CT3081, CT3082 and CT3083 series consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 6-lead DIP DMC-Isolator[®] package with different lead forming options.

Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control



Note: Different lead forming options available. See package dimension.



Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters		Ratings	Units	Notes
Viso	Isolation voltage	5000	V _{RMS}		
Topr	Operating temperature		-55 ~ +100	°C	
Tstg	Storage temperature		-55 ~ +150	°C	
Tsol	Soldering temperature		260	°C	
Emitter					
lF	Forward current		60	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А		
VR	Reverse voltage	6	V		
PD	Power dissipation	100	mW		
Detector	ſ				
PD	Power dissipation		300	mW	
<i>\</i> /		CT3061,3062,3063	600	V	
Vdrm	Off-State Output Terminal Voltage	CT3081,3082,3083	800	V	
I _{TM}	RMS on-state current	100	mA		
ITSM	Peak Repetitive Surge Current	1	А		
TJ	Junction temperature	<110	°C		



Electrical Characteristics $T_A = 25^{\circ}C$, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	IF=10mA	-	-	1.5	V	
I _R	Reverse Current	$V_R = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

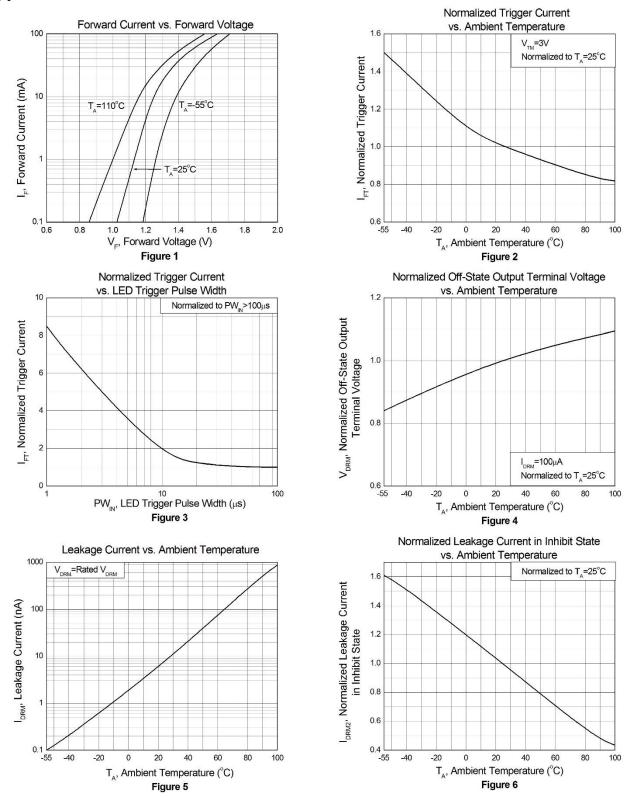
Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
la a u	Peak Blocking	CT3061,62,63	I- 0mA Varue Botod Varu	-	-	500	nA	
I _{DRM1}	Current	CT3081,82,83	I _F = 0mA, V _{DRM} = Rated V _{DRM}					
I _{DRM2}	Inhibit Leakage Current		IF= Rated IFT, VDRM= Rated	-	-	500		
IDRM2			Vdrm				μA	
VINH	Inhibit Voltage		IF= Rated IFT,	-	-	20	V	
V _{TM}	Peak On-State Voltage		I_{F} = Rated I_{FT} , I_{TM} = 100mA	-	-	3	V	
	Critical Rate of	CT3061,62,63		1000	-	-		
dv/dt	Rise off-State	CT3081,82,83	VPEAK= Rated VDRM	600	_	-	V/µs	
	Voltage			000	-			

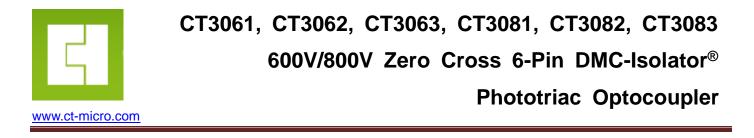
Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	Input	CT3061, CT3081	Terminal Valtage 2V	-	-	15		
IFT	Trigger	CT3062, CT3082	- Terminal Voltage = 3V - I _{TM} =100mA -	-	-	10	mA	
	Current	CT3063, CT3083		-	-	5		
	Holding Current		Terminal Voltage from "ON" to "OFF"	200	380			
Ін		litent	"ON" state I _F =0mA	-	300	- 380	μΑ	
Rio	Isolation Resistance		VIO= 500VDC	1x10 ¹¹	-	-	Ω	
Сю	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

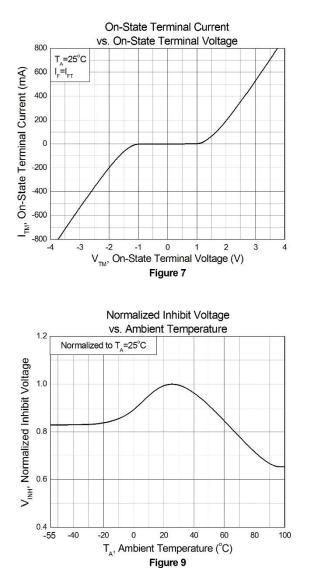


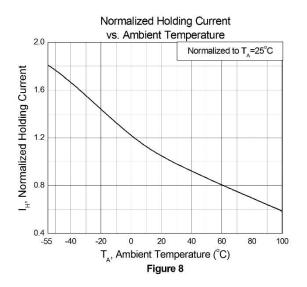
Typical Characteristic Curves T_A = 25°C, unless otherwise specified





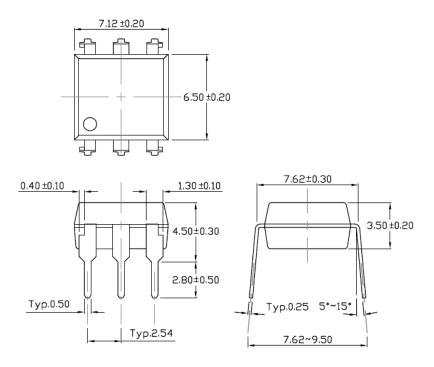
Typical Characteristic Curves T_A = 25°C, unless otherwise specified (Continued)







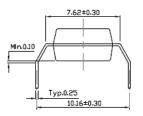
Package Dimension Dimensions in mm unless otherwise stated



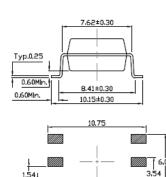
Forming Option Dimensions in mm unless otherwise stated

1.00

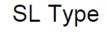
М Туре







7.55



8.41±0.30 10.15±0.30

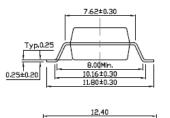
10.38

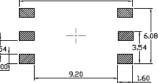
7.55

3,54

1.60

SLM Type





Typ.0,25

0.20Ma×

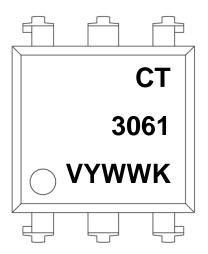
1.54

1.00

1.60



Marking Information



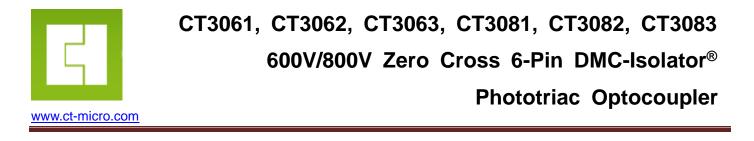
Note:	
СТ	: Denotes "CT Micro"
3061	: Part Number
V	: VDE Safety Mark Option (Blank or V)
Y	: One Digit Year Code
WW	: Two Digit Work Week
К	: Manufacturing Code

Ordering Information

CT306X(V)(Y)(Z)-G, CT308X(V)(Y)(Z)-G

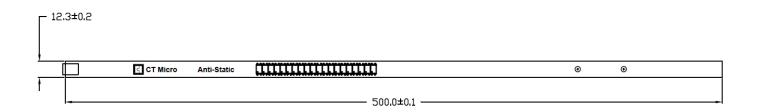
СТ	= Denotes "CT Micro"
3061	= Part Number
Х	= Part No. (CT306X:1,2,3), (CT308X : 1,2,3)
V	= VDE Safety Mark Option (Blank or V)
Y	= Lead Form Option (Blank, S, SL, M or SLM)
Z	= Tape and Reel Option (Blank, T1 or T2)
G	= Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
М	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1000 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1000 Units/Reel



Carrier Specifications Dimensions in mm unless otherwise stated

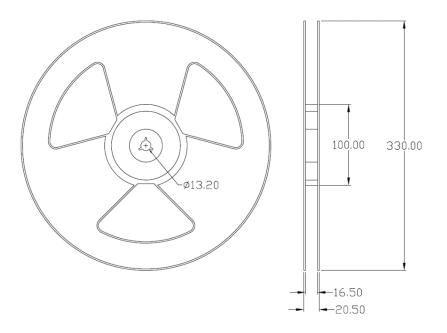
Tube Option Standard DIP



Tube Option M Type

[^{1:}	3.9±0.2					
		CT Micro	Anti-Static		۲	۲
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	4			500,0±0,1		*

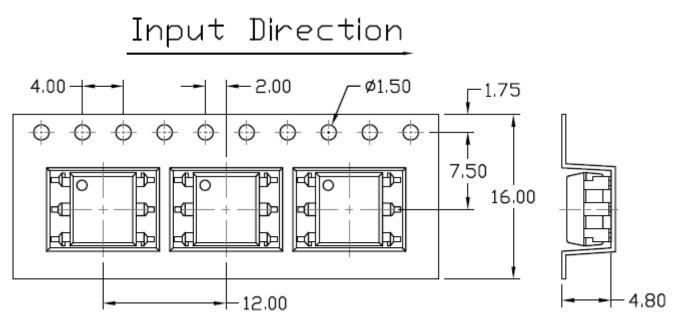
Reel Dimension Dimensions in mm unless otherwise stated



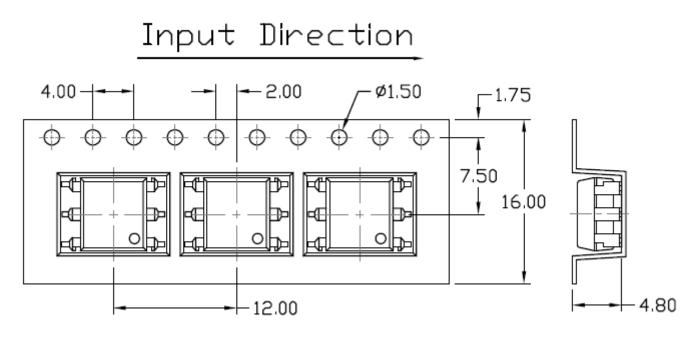


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)

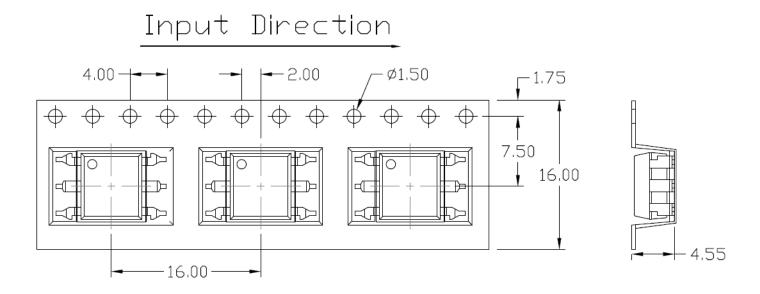


Option S(T2) & SL(T2)

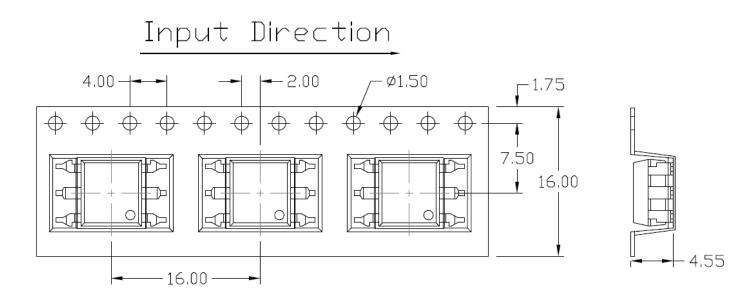




Option SLM(T1)



Option SLM(T2)





Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

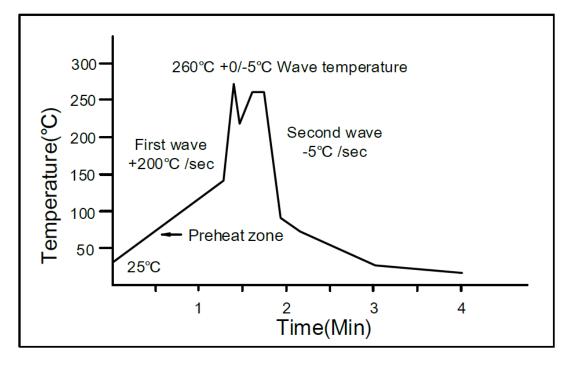
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

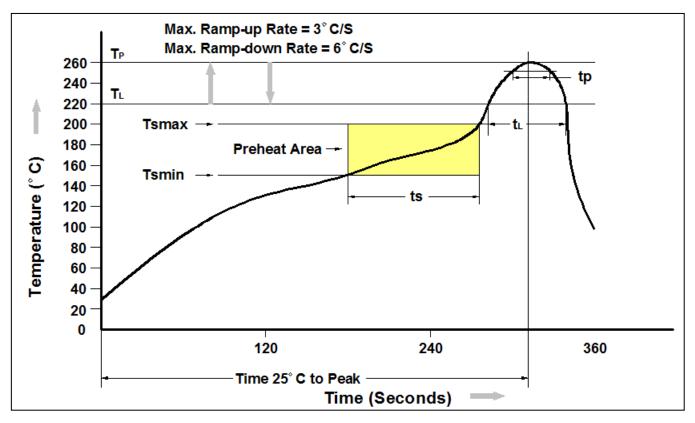
One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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